$4 \text{ M SRAM} (512\text{-kword} \times 8\text{-bit})$ 

# **HITACHI**

ADE-203-640B (Z) Rev. 2.0 Nov. 1997

### **Description**

The Hitachi HM628512A is a 4-Mbit static RAM organized 512-kword  $\times$  8-bit. It realizes higher density, higher performance and low power consumption by employing 0.5  $\mu$ m Hi-CMOS process technology. The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II or 600-mil plastic DIP, is available for high density mounting. The HM628512A is suitable for battery backup system.

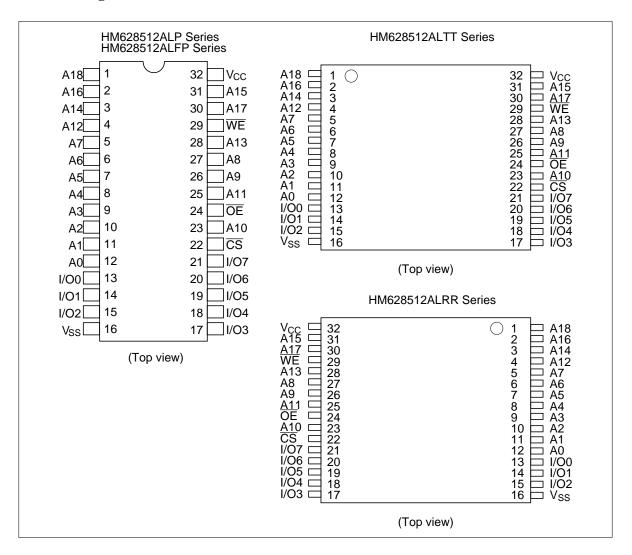
#### **Features**

- Single 5 V supply
- Access time: 55/70 ns (max)
- Power dissipation
  - Active: 50 mW/MHz (typ)
  - Standby:  $10 \mu W (typ)$
- · Completely static memory. No clock or timing strobe required
- Equal access and cycle times
- Common data input and output: Three state output
- Directly TTL compatible: All inputs and outputs
- Battery backup operation

# **Ordering Information**

Type No.	Access time	Package
HM628512ALP-5 HM628512ALP-7	55 ns 70 ns	600-mil 32-pin plastic DIP (DP-32)
HM628512ALP-5SL HM628512ALP-7SL	55 ns 70 ns	_
HM628512ALFP-5 HM628512ALFP-7	55 ns 70 ns	525-mil 32-pin plastic SOP (FP-32D)
HM628512ALFP-5SL HM628512ALFP-7SL	55 ns 70 ns	_
HM628512ALTT-5 HM628512ALTT-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II (TTP-32D)
HM628512ALTT-5SL HM628512ALTT-7SL	55 ns 70 ns	_
HM628512ALRR-5 HM628512ALRR-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II reverse (TTP-32DR)
HM628512ALRR-5SL HM628512ALRR-7SL	55 ns 70 ns	

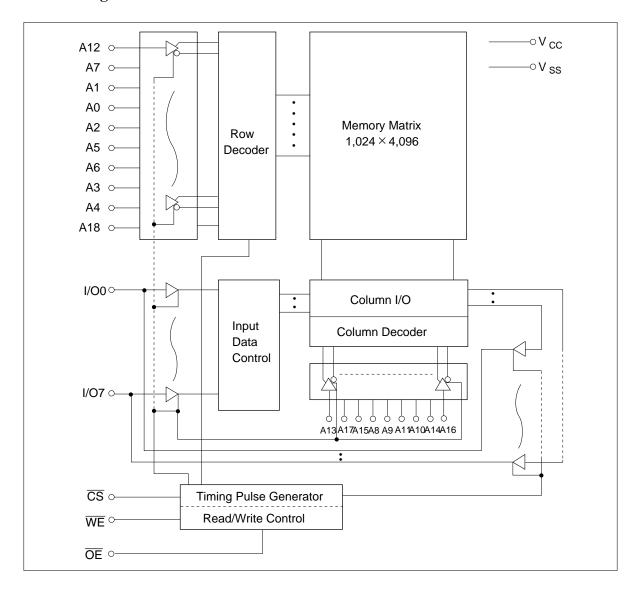
### **Pin Arrangement**



### **Pin Description**

Pin name	Function
A0 to A18	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
ŌĒ	Output enable
WE	Write enable
V <sub>cc</sub>	Power supply
V <sub>ss</sub>	Ground

### **Block Diagram**



### **Function Table**

WE	CS	OE	Mode	V <sub>cc</sub> current	Dout pin	Ref. cycle
×	Н	×	Not selected	$I_{SB}, I_{SB1}$	High-Z	_
Н	L	Н	Output disable	I <sub>cc</sub>	High-Z	_
Н	L	L	Read	I <sub>cc</sub>	Dout	Read cycle
L	L	Н	Write	I <sub>cc</sub>	Din	Write cycle (1)
L	L	L	Write	I <sub>cc</sub>	Din	Write cycle (2)

Note: x: H or L

### **Absolute Maximum Ratings**

Parameter	Symbol Value		Unit
Power supply voltage	V <sub>cc</sub>	-0.5 to +7.0	V
Voltage on any pin relative to V <sub>ss</sub>	V <sub>T</sub>	$-0.5^{*1}$ to $V_{CC} + 0.3^{*2}$	V
Power dissipation	P <sub>T</sub>	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	-55 to +125	°C
Storage temperature under bias	Tbias	-10 to +85	°C

Notes: 1. -3.0 V for pulse half-width  $\leq 30 \text{ ns}$ 

2. Maximum voltage is 7.0 V

### **Recommended DC Operating Conditions** (Ta = 0 to +70°C)

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V <sub>cc</sub>	4.5	5.0	5.5	V
	V <sub>ss</sub>	0	0	0	V
Input high voltage	V <sub>IH</sub>	2.2	<del></del>	V <sub>cc</sub> + 0.3	V
Input low voltage	V <sub>IL</sub>	-0.3 <sup>*1</sup>	<del></del>	0.8	V

Note: 1. -3.0 V for pulse half-width  $\leq 30 \text{ ns}$ 

# DC Characteristics (Ta = 0 to +70°C, $V_{CC}$ = 5 V $\pm 10\%$ , $V_{SS}$ = 0 V)

Parameter		Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leakage current		I <sub>LI</sub>	_	_	1	μΑ	$Vin = V_{SS}$ to $V_{CC}$
Output leakage current		I <sub>LO</sub>	_		1	μΑ	$\overline{\text{CS}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{OE}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{WE}} = \text{V}_{\text{IL}}, \text{V}_{\text{I/O}} = \text{V}_{\text{SS}} \text{ to V}_{\text{CC}}$
Operating power supply current: DC		I <sub>cc</sub>	_	8	15	mA	$\overline{\text{CS}} = \text{V}_{\text{IL}},$ others = $\text{V}_{\text{IH}}/\text{V}_{\text{IL}}, \text{I}_{\text{I/O}} = 0 \text{ mA}$
Operating power supply current	HM628512A-5	I <sub>CC1</sub>	_	45	70	mA	$\frac{\text{Min cycle, duty} = 100\%}{\overline{\text{CS}}} = V_{\text{IL}}, \text{ others} = V_{\text{IH}}/V_{\text{IL}}$ $I_{\text{I/O}} = 0 \text{ mA}$
	HM628512A-7	I <sub>CC1</sub>	_	40	60	mA	
Operating power supply current		I <sub>CC2</sub>	_	10	20	mA	$\begin{split} & \text{Cycle time} = 1 \; \mu\text{s}, \\ & \text{duty} = 100\% \\ & I_{\text{I/O}} = 0 \; \text{mA}, \; \overline{\text{CS}} \leq 0.2 \; \text{V} \\ & V_{\text{IH}} \geq V_{\text{CC}} - 0.2 \; \text{V}, \; V_{\text{IL}} \leq 0.2 \; \text{V} \\ & V \end{split}$
Standby power supply cur	rent: DC	I <sub>SB</sub>		1	3	mA	CS = V <sub>IH</sub>
Standby power supply current (1): DC		I <sub>SB1</sub>	_	2*2	100*2	μΑ	$Vin \ge 0 \text{ V}, \overline{CS} \ge V_{CC} - 0.2 \text{ V}$
			_	2* <sup>3</sup>	50* <sup>3</sup>	μΑ	-
Output low voltage		V <sub>OL</sub>		_	0.4	V	I <sub>OL</sub> = 2.1 mA
Output high voltage		V <sub>OH</sub>	2.4			V	$I_{OH} = -1.0 \text{ mA}$
Output high voltage		V <sub>OH</sub>	2.4	_	_	V	I <sub>OH</sub> = -1.0 IIIA

Notes: 1. Typical values are at  $V_{CC} = 5.0 \text{ V}$ ,  $Ta = +25^{\circ}\text{C}$  and specified loading, and not guaranteed.

- 2. This characteristics is guaranteed only for L version.
- 3. This characteristics is guaranteed only for L-SL version.

### **Capacitance** (Ta = 25°C, f = 1 MHz)

Parameter	Symbol	Тур	Max	Unit	Test conditions
Input capacitance*1	Cin	_	8	pF	Vin = 0 V
Input/output capacitance*1	C <sub>I/O</sub>		10	pF	$V_{I/O} = 0 V$

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C,  $V_{CC}$  = 5 V  $\pm$  10%, unless otherwise noted.)

### **Test Conditions**

• Input pulse levels: 0.8 V to 2.4 V

• Input rise and fall time: 5 ns

• Input and output timing reference levels: 1.5 V

 Output load: 1 TTL Gate +  $C_L$  (100 pF) (HM628512A-7)

 $1 \text{ TTL Gate} + C_L (50 \text{ pF}) (HM628512A-5)$ 

(Including scope & jig)

#### **Read Cycle**

		HM62	8512A				
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read cycle time	t <sub>RC</sub>	55	_	70	_	ns	
Address access time	t <sub>AA</sub>	_	55	_	70	ns	
Chip select access time	t <sub>co</sub>	_	55	_	70	ns	"
Output enable to output valid	t <sub>OE</sub>	_	25		35	ns	"
Chip selection to output in low-Z	t <sub>LZ</sub>	10	_	10	_	ns	2
Output enable to output in low-Z	t <sub>OLZ</sub>	5	_	5	_	ns	2
Chip deselection to output in high-Z	t <sub>HZ</sub>	0	20	0	25	ns	1, 2
Output disable to output in high-Z	t <sub>OHZ</sub>	0	20	0	25	ns	1, 2
Output hold from address change	t <sub>oH</sub>	10		10		ns	

#### Write Cycle

#### HM628512A

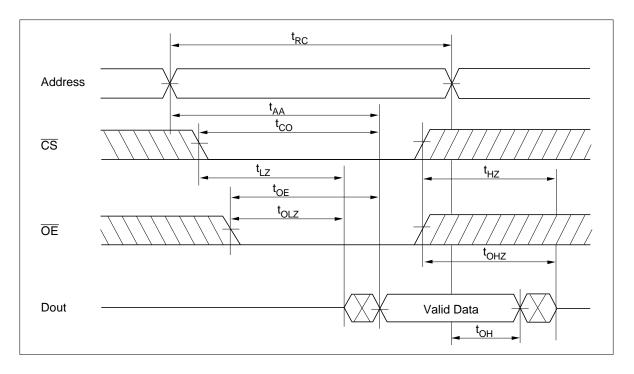
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write cycle time	t <sub>wc</sub>	55	_	70	_	ns	
Chip selection to end of write	t <sub>cw</sub>	50	_	60	_	ns	4
Address setup time	t <sub>AS</sub>	0	_	0	_	ns	5
Address valid to end of write	t <sub>AW</sub>	50	_	60	_	ns	
Write pulse width	t <sub>WP</sub>	40	_	50	_	ns	3, 12
Write recovery time	$t_{WR}$	0	_	0	_	ns	6
WE to output in high-Z	t <sub>wHZ</sub>	0	20	0	25	ns	1, 2, 7
Data to write time overlap	$\mathbf{t}_{DW}$	25	_	30	_	ns	
Data hold from write time	t <sub>DH</sub>	0	_	0	_	ns	
Output active from output in high-Z	t <sub>ow</sub>	5	_	5		ns	2
Output disable to output in high-Z	t <sub>OHZ</sub>	0	20	0	25	ns	1, 2, 7

Notes: 1.  $t_{HZ}$ ,  $t_{OHZ}$  and  $t_{WHZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

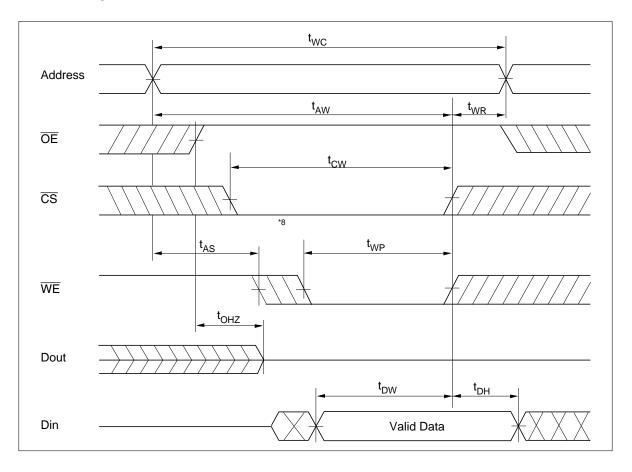
- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap (t<sub>WP</sub>) of a low \(\overline{CS}\) and a low \(\overline{WE}\). A write begins at the later transition of \(\overline{CS}\) going low or \(\overline{WE}\) going low. A write ends at the earlier transition of \(\overline{CS}\) going high or \(\overline{WE}\) going high. t<sub>WP</sub> is measured from the beginning of write to the end of write.
- 4.  $t_{CW}$  is measured from  $\overline{CS}$  going low to the end of write.
- 5.  $t_{AS}$  is measured from the address valid to the beginning of write.
- 6.  $t_{WR}$  is measured from the earlier of  $\overline{WE}$  or  $\overline{CS}$  going high to the end of write cycle.
- 7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 8. If the  $\overline{\text{CS}}$  low transition occurs simultaneously with the  $\overline{\text{WE}}$  low transition or after the  $\overline{\text{WE}}$  transition, the output remain in a high impedance state.
- 9. Dout is the same phase of the write data of this write cycle.
- 10. Dout is the read data of next address.
- 11. If CS is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
- 12. In the write cycle with  $\overline{OE}$  low fixed,  $t_{WP}$  must satisfy the following equation to avoid a problem of data bus contention.  $t_{WP} \ge t_{DW}$  min +  $t_{WHZ}$  max

## **Timing Waveforms**

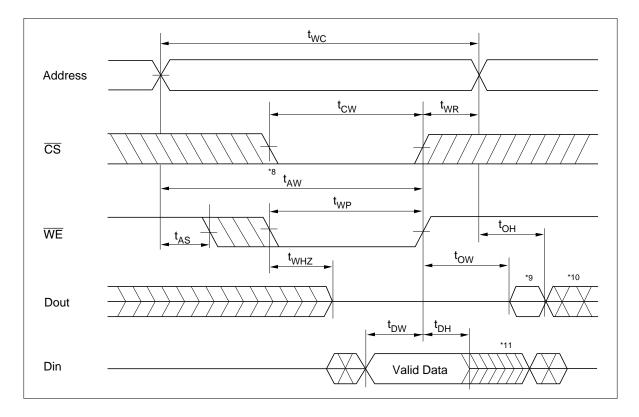
## Read Timing Waveform $(\overline{WE}=V_{IH})$



Write Timing Waveform (1)  $(\overline{OE} \operatorname{Clock})$ 



### Write Timing Waveform (2) $(\overline{OE} Low Fixed)$



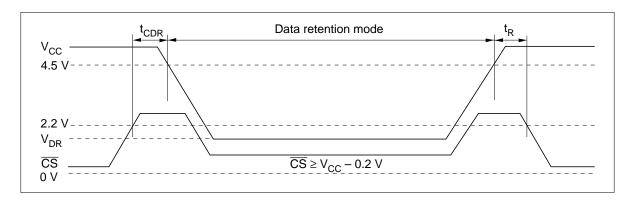
Low  $V_{cc}$  Data Retention Characteristics (Ta = 0 to +70°C)

Parameter	Symbol	Min	Тур	Max	Unit	Test conditions*3
V <sub>cc</sub> for data retention	$V_{DR}$	2	_	_	V	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V, Vin} \ge 0 \text{ V}$
Data retention current	I <sub>CCDR</sub>	_	1*4	50* <sup>1</sup>	μΑ	$\frac{V_{CC} = 3.0 \text{ V, Vin} \ge 0 \text{ V}}{CS} \ge V_{CC} - 0.2 \text{ V}$
		_	1*4	15* <sup>2</sup>	μΑ	_
Chip deselect to data retention time	t <sub>CDR</sub>	0	_	_	ns	See retention waveform
Operation recovery time	t <sub>R</sub>	5	_	_	ms	

Notes: 1. For L-version and 20  $\mu$ A (max.) at Ta = 0 to 40°C.

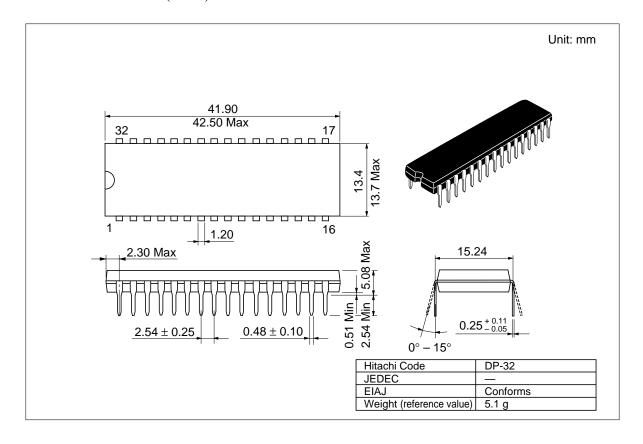
- 2. For SL-version and 3  $\mu A$  (max.) at Ta = 0 to 40°C.
- 3.  $\overline{\text{CS}}$  controls address buffer,  $\overline{\text{WE}}$  buffer,  $\overline{\text{OE}}$  buffer, and Din buffer. In data retention mode, Vin levels (address,  $\overline{\text{WE}}$ ,  $\overline{\text{OE}}$ , I/O) can be in the high impedance state.
- 4. Typical values are at  $V_{cc}$  = 3.0 V, Ta = 25°C and specified loading, and not guaranteed.

Low  $V_{CC}$  Data Retention Timing Waveform  $(\overline{CS}$  Controlled)



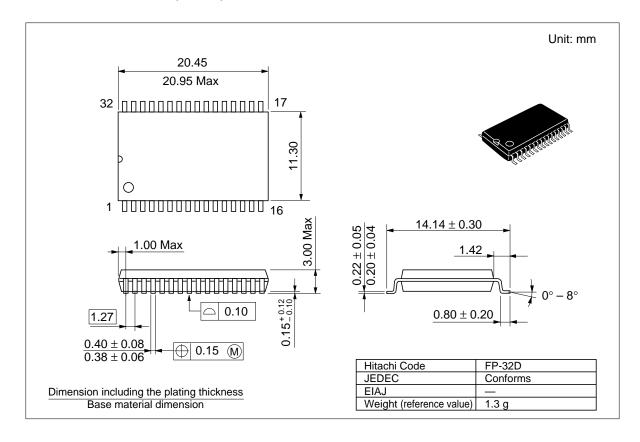
### **Package Dimensions**

### HM628512ALP Series (DP-32)



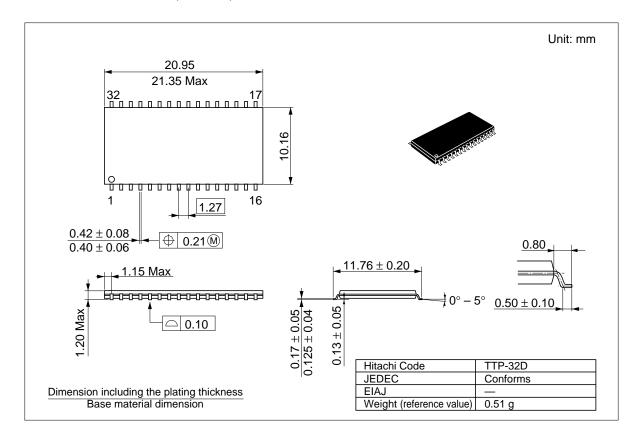
### Package Dimensions (cont.)

### HM628512ALFP Series (FP-32D)



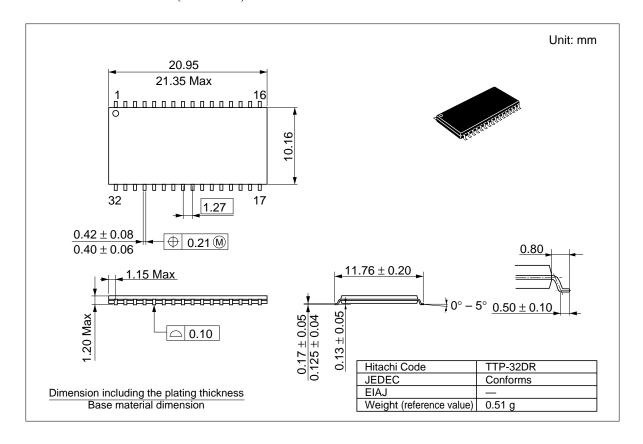
### Package Dimensions (cont.)

### HM628512ALTT Series (TTP-32D)



### Package Dimensions (cont.)

### HM628512ALRR Series (TTP-32DR)



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0.0	Sep. 12, 1996	Initial issue	K. Imato	K. Imato
1.0	Dec. 2, 1996	Deletion of preliminary	K. Imato	K. Imato
2.0	Nov. 1997	Change of Subtitle		